ABSTRACT

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH LEADS SEPARATED FROM A DIE PADDLE

An integrated circuit package system is provided including forming a leadframe having a frame and a die paddle having leads thereon. The leads are held with respect to the die paddle. The leads are separated from the die paddle, and a die is attached to the die paddle. Bond wires are bonded between the leads and the die. The die and bond wires are encapsulated. The leadframe is singulated to separate the frame and the die paddle. (Fig. 26)